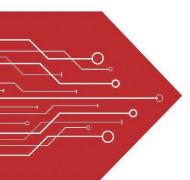
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com





 $V_{DS} = 40V I_{D} = 10A$

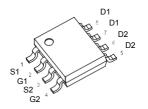
 $R_{DS(ON)}$ < 19m Ω @ V_{GS} =10V

Application

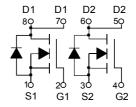
Battery protection

Load switch

Uninterruptible power supply



SOP-8



N-Channel MOSFET

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|-------------------------|------------|------|
| Drain-Source Voltage | VDS | 40 | V |
| Gate-Source Voltage | Vgs | ±20 | V |
| Drain Current-Continuous | ID | 10 | А |
| Drain Current-Continuous(Tc=100°C) | I _D (100 °C) | 6.4 | A |
| Pulsed Drain Current | Ірм | 40 | A |
| Maximum Power Dissipation | P _D | 2 | W |
| Operating Junction and Storage Temperature Range | Тл,Тятв | -55 To 150 | °C |
| Thermal Resistance, Junction-to-Ambient (Note 2) | Reja | 62.5 | °C/W |

Compiance

N-CH Electrical Characteristics (T_A =25 $^{\circ}$ C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|----------------------------------|-------------------|--|-----|------|------|------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 40 | - | - | V |
| Zero Gate Voltage Drain Current | loss | V _{DS} =40V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | lgss | V_{GS} =±20 V , V_{DS} =0 V | - | - | ±100 | nA |
| Gate Threshold Voltage | VGS(th) | V_{DS} = V_{GS} , I_{D} = $250\mu A$ | 1 | 1.5 | 2.0 | V |
| | | V _{GS} =10V, I _D =8A | - | 15 | 20 | mΩ |
| Drain-Source On-State Resistance | Rds(on) | V _{GS} =4.5V, I _D =4A | - | 20 | 30 | mΩ |
| Forward Transconductance | grs | V _{DS} =5V,I _D =8A | 33 | - | - | S |
| Input Capacitance | Clss | | - | 964 | - | PF |
| Output Capacitance | Coss | V_{DS} =20V, V_{GS} =0V, F=1.0MHz | - | 109 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.UIVIFIZ | - | 96 | - | PF |
| Turn-on Delay Time | td(on) | | - | 5.5 | - | nS |
| Turn-on Rise Time | t _r | V _{DD} =20V, R _L =2.5Ω | - | 14 | - | nS |
| Turn-Off Delay Time | td(off) | V_{GS} =10 V , R_{GEN} =3 Ω | - | 24 | - | nS |
| Turn-Off Fall Time | tf | | - | 12 | - | nS |
| Total Gate Charge | Qg | | - | 22.9 | - | nC |
| Gate-Source Charge | Q _{gs} | V _{DS} =20V,I _D =8A, | - | 3.5 | - | nC |
| Gate-Drain Charge | Q _{gd} | V _{GS} =10V | - | 5.3 | - | nC |
| Diode Forward Voltage (Note 3) | VsD | V _{GS} =0V,I _S =9A | - | 0.8 | 1.2 | V |



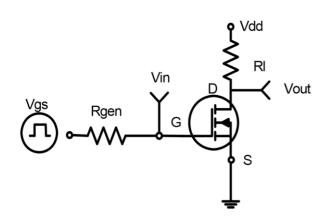
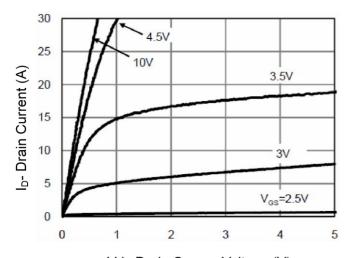


Figure 1:Switching Test Circuit



Vds Drain-Source Voltage (V)
Figure 3 Output Characteristics

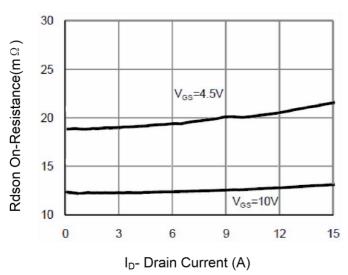


Figure 5 Drain-Source On-Resistance

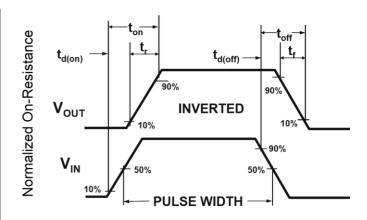


Figure 2:Switching Waveforms

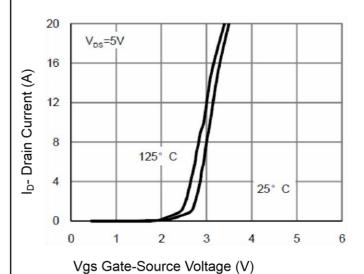


Figure 4 Transfer Characteristics

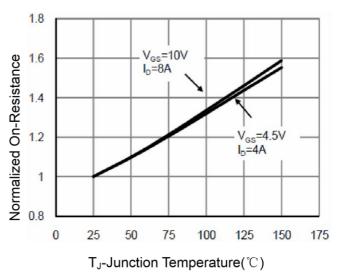
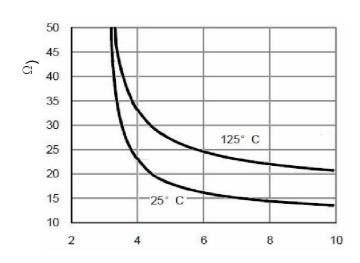


Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V) Figure 7 Rdson vs Vgs

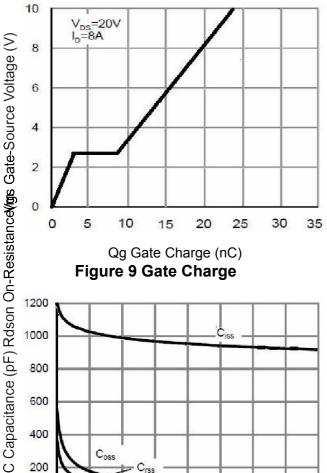


Figure 9 Gate Charge

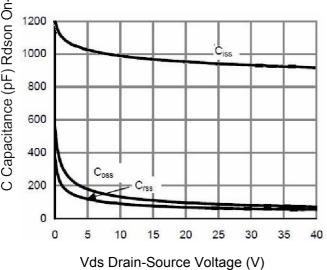
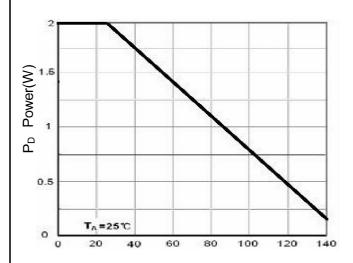
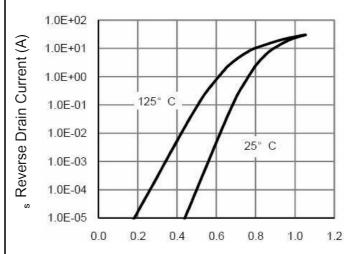


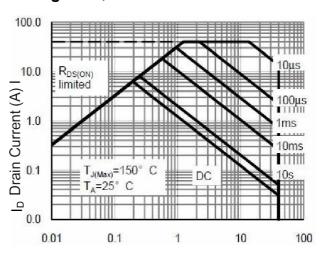
Figure 11 Capacitance vs Vds



T_J-Junction Temperature(°C) **Figure 8 Power Dissipation**



Vds Drain-Source Voltage (V) Figure 10 Source- Drain Diode Forward



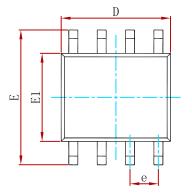
Vds Drain-Source Voltage (V) Figure 12 Safe Operation Area

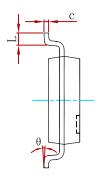


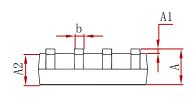




PACKAGE MECHANICAL DATA

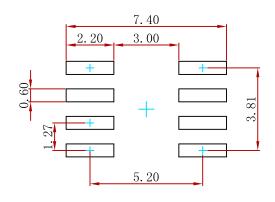






| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|--------|----------------------|--------|--|
| Symbol | Min | Max | Min | Max | |
| A | 1.350 | 1.750 | 0.053 | 0.069 | |
| A1 | 0.100 | 0. 250 | 0.004 | 0.010 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| b | 0.330 | 0.510 | 0.013 | 0.020 | |
| c | 0.170 | 0. 250 | 0.007 | 0.010 | |
| D | 4.800 | 5.000 | 0. 189 | 0. 197 | |
| e | 1.270 (BSC) | | 0.050 (BSC) | | |
| Е | 5. 800 | 6. 200 | 0. 228 | 0.244 | |
| E1 | 3.800 | 4.000 | 0. 150 | 0.157 | |
| L | 0.400 | 1.270 | 0.016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|-----------|-------|------|
| AO4884-MS | SOP-8 | 4000 |



Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.

单击下面可查看定价,库存,交付和生命周期等信息

>>MSKSEMI (美森科)